 frame being sized and arranged relative to one another such that a process space bounded substantially by the atomization surface of the target body and the surrounding non-atomized residual interior surface, F_9 , of the receiving frame, except for the receiving opening for the at least one workpiece, satisfies the relationship $\leq 50\% F_1$, to minimize the surrounding non-atomized residual interior surface thereby to ensure, during an atomizing operation, a stable plasma discharge.

REMARKS

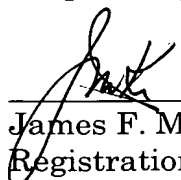
The minor informality in Claim 45 has now been addressed. Entry of this amendment to correct a misspelling is solicited and anticipated.

If there are any questions regarding this amendment or the application in general, a telephone call to the undersigned would be appreciated since this should expedite the prosecution of the application for all concerned.

If necessary to effect a timely response, this paper should be considered as a petition for an Extension of Time sufficient to effect a timely response, and please charge any deficiency in fees or credit any overpayments to Deposit Account No. 05-1323 (Docket #622/42052DV).

Respectfully submitted,

September 3, 2002



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VERSION WITH MARKINGS TO SHOW CHANGES

IN THE CLAIMS:

45. (Amended) The target body according to Claim 44, wherein the magnetron source comprises a magnetic circuit arrangement operable to generate a magnetic field over the atomization surface, including an anode arrangement, a receiving frame which extends around an edge of the target body and is electrically insulated with respect thereto, which receiving frame has a receiving opening for at least one [workpiee] workpiece to be coated, and the atomization surface and a surrounding non-atomized residual interior surface of the receiving frame being sized and arranged relative to one another such that a process space bounded substantially by the atomization surface of the target body and the surrounding non-atomized residual interior surface, F_9 , of the receiving frame, except for the receiving opening for the at least one workpiece, satisfies the relationship $\leq 50\% F_1$, to minimize the surrounding non-atomized residual interior surface thereby to ensure, during an atomizing operation, a stable plasma discharge.